# **MA26V15**

## Silicon epitaxial planar type

### For VCO

#### Features

- $\bullet$  Good linearity and large capacitance-ratio in  $C_D$   $V_R$  relation
- Small series resistance rD

Parameter

• High frequency type by this low capacitance

## Unit: mm 0.60±0. 1.00±0.0 0.39+0 0.65±0.01 1: Anode 2: N.C. 3: Cathode ML3-N2 Package

Marking Symbol: 2N

Absolute Maximum Ratings  $T_a = 25^{\circ}C$ 

	_ <b>,</b>			
Reverse voltage	V <sub>R</sub>	6	V	
Junction temperature	Tj	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Symbol Bating

## Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	IR	$V_R = 5 V$	00	c0/	10	nA
Diode capacitance	C <sub>D(0.5V)</sub>	$V_{R} = 0.5 V, f = 1 MHz$	7.30	0-	7.91	pF
	C <sub>D(2.5V)</sub>	$V_{R} = 2.5 V, f = 1 MHz$	2.98		3.23	
Capacitance ratio	C <sub>D(0.5V)</sub> /C <sub>D(2.5V)</sub>		2.35		2.55	—
Series resistance *	r <sub>D</sub>	$V_R = 1 V, f = 470 MHz$			0.45	Ω

Unit

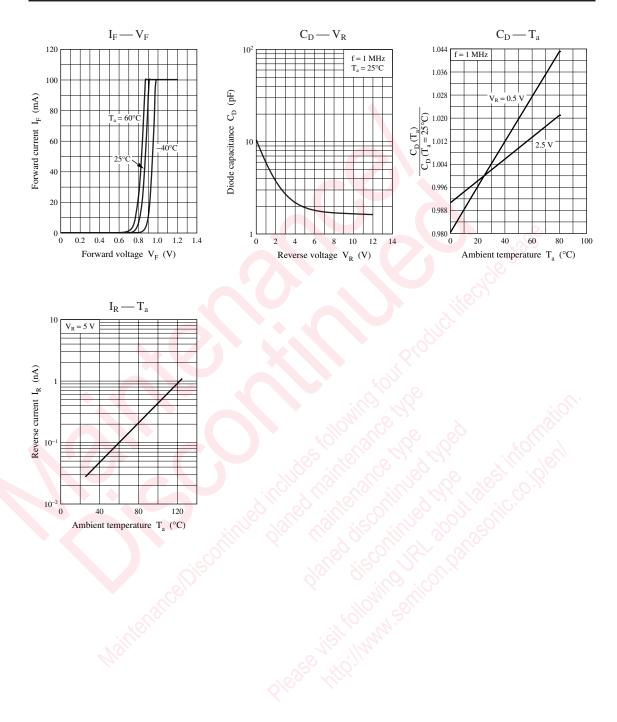
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 470 MHz

3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

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